

ABSTRACT

A bonding material of the present invention includes: a copper foil; and a sinterable bonding film formed on one surface of the copper foil. The bonding film contains a copper powder and a solid reducing agent. The bonding material is used for bonding to a bonding target having, on its surface, at least one metal selected from the group consisting of gold, silver, copper, nickel, and aluminum. The bonding material of the present invention is also used as a material for wire bonding. The present invention also provides a bonded structure in which a bonding target having a metal layer formed on its surface and a copper foil are electrically connected to each other via a bonding layer formed of a sintered structure of a copper powder, wherein the metal layer contains at least one metal selected from the group consistin of gold, silver, copper, nickel, and aluminum.